

SL74HCT573

Octal 3-State Noninverting Transparent Latch

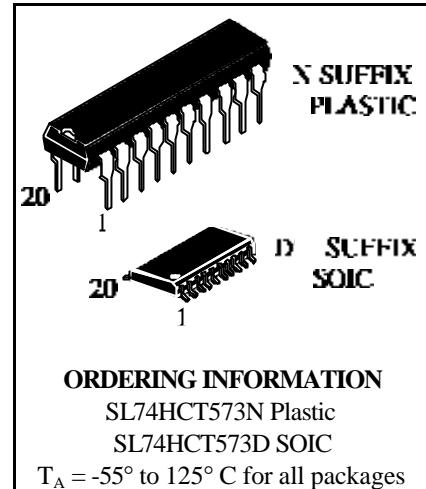
High-Performance Silicon-Gate CMOS

The SL74HCT573 is identical in pinout to the LS/ALS573. This device may be used as a level converter for interfacing TTL or NMOS outputs to High-Speed CMOS inputs.

These latches appear transparent to data (i.e., the outputs change asynchronously) when Latch Enable is high. When Latch Enable goes low, data meeting the setup and hold time becomes latched.

The Output Enable input does not affect the state of the latches, but when Output Enable is high, all device outputs are forced to the high-impedance state. Thus, data may be latched even when the outputs are not enabled.

- TTL/NMOS-Compatible Input Levels
- Outputs Directly Interface to CMOS, NMOS, and TTL
- Operating Voltage Range: 4.5 to 5.5 V
- Low Input Current: 1.0 μ A



ORDERING INFORMATION

SL74HCT573N Plastic

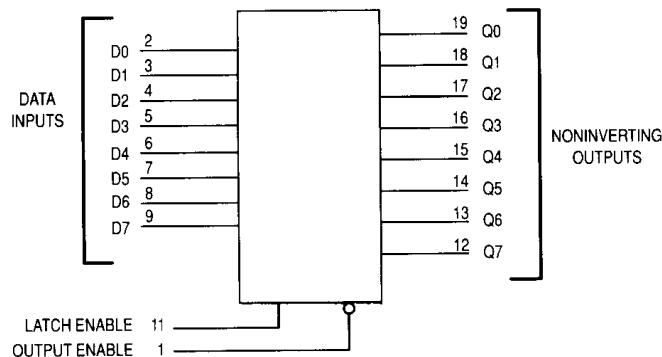
SL74HCT573D SOIC

$T_A = -55^\circ$ to 125° C for all packages

PIN ASSIGNMENT

OUTPUT ENABLE	1	20	V_{CC}
D0	2	19	Q_0
D1	3	18	Q_1
D2	4	17	Q_2
D3	5	16	Q_3
D4	6	15	Q_4
D5	7	14	Q_5
D6	8	13	Q_6
D7	9	12	Q_7
GND	10	L	LATCH ENABLE

LOGIC DIAGRAM



PIN 20= V_{CC}
PIN 10=GND

FUNCTION TABLE

Inputs		Output	
Output Enable	Latch Enable	D	Q
L	H	H	H
L	H	L	L
L	L	X	no change
H	X	X	Z

X = don't care

Z = high impedance

SLS

System Logic
Semiconductor

MAXIMUM RATINGS*

Symbol	Parameter	Value	Unit
V _{CC}	DC Supply Voltage (Referenced to GND)	-0.5 to +7.0	V
V _{IN}	DC Input Voltage (Referenced to GND)	-1.5 to V _{CC} +1.5	V
V _{OUT}	DC Output Voltage (Referenced to GND)	-0.5 to V _{CC} +0.5	V
I _{IN}	DC Input Current, per Pin	±20	mA
I _{OUT}	DC Output Current, per Pin	±35	mA
I _{CC}	DC Supply Current, V _{CC} and GND Pins	±75	mA
P _D	Power Dissipation in Still Air, Plastic DIP+ SOIC Package+	750 500	mW
T _{tsg}	Storage Temperature	-65 to +150	°C
T _L	Lead Temperature, 1 mm from Case for 10 Seconds (Plastic DIP or SOIC Package)	260	°C

*Maximum Ratings are those values beyond which damage to the device may occur.

Functional operation should be restricted to the Recommended Operating Conditions.

+Derating - Plastic DIP: - 10 mW/°C from 65° to 125°C

SOIC Package: : - 7 mW/°C from 65° to 125°C

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Unit
V _{CC}	DC Supply Voltage (Referenced to GND)	4.5	5.5	V
V _{IN} , V _{OUT}	DC Input Voltage, Output Voltage (Referenced to GND)	0	V _{CC}	V
T _A	Operating Temperature, All Package Types	-55	+125	°C
t _r , t _f	Input Rise and Fall Time (Figure 1)	0	500	ns

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high-impedance circuit. For proper operation, V_{IN} and V_{OUT} should be constrained to the range GND≤(V_{IN} or V_{OUT})≤V_{CC}.

Unused inputs must always be tied to an appropriate logic voltage level (e.g., either GND or V_{CC}). Unused outputs must be left open.



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DC ELECTRICAL CHARACTERISTICS (Voltages Referenced to GND)

Symbol	Parameter	Test Conditions	V _{CC} V	Guaranteed Limit			Unit
				25 °C to -55°C	≤85 °C	≤125 °C	
V _{IH}	Minimum High-Level Input Voltage	V _{OUT} =0.1 V or V _{CC} -0.1 V I _{OUT} ≤ 20 μA	4.5 5.5	2.0 2.0	2.0 2.0	2.0 2.0	V
V _{IL}	Maximum Low -Level Input Voltage	V _{OUT} =0.1 V or V _{CC} -0.1 V I _{OUT} ≤ 20 μA	4.5 5.5	0.8 0.8	0.8 0.8	0.8 0.8	V
V _{OH}	Minimum High-Level Output Voltage	V _{IN} =V _{IH} or V _{IL} I _{OUT} ≤ 20 μA	4.5 5.5	4.4 5.4	4.4 5.4	4.4 5.4	V
		V _{IN} =V _{IH} or V _{IL} I _{OUT} ≤ 6.0 mA	4.5	3.98	3.84	3.7	
V _{OL}	Maximum Low-Level Output Voltage	V _{IN} = V _{IL} or V _{IH} I _{OUT} ≤ 20 μA	4.5 5.5	0.1 0.1	0.1 0.1	0.1 0.1	V
		V _{IN} = V _{IL} or V _{IH} I _{OUT} ≤ 6.0 mA	4.5	0.26	0.33	0.4	
I _{IN}	Maximum Input Leakage Current	V _{IN} =V _{CC} or GND	5.5	±0.1	±1.0	±1.0	μA
I _{OZ}	Maximum Three State Leakage Current	Output in High-Impedance State V _{IN} =V _{IH} or V _{IL} V _{OUT} =V _{CC} or GND	5.5	±0.5	±5.0	±10	μA
I _{CC}	Maximum Quiescent Supply Current (per Package)	V _{IN} =V _{CC} or GND I _{OUT} =0μA	5.5	4.0	40	160	μA
ΔI _{CC}	Additional Quiescent Supply Current	V _{IN} =2.4 V, Any One Input V _{IN} =V _{CC} or GND, Other Inputs I _{OUT} =0μA	5.5	≥-55°C		25°C to 125°C	mA
				2.9		2.4	

AC ELECTRICAL CHARACTERISTICS($V_{CC} = 5.0 \text{ V} \pm 10\%$, $C_L = 50 \text{ pF}$, Input $t_r = t_f = 6.0 \text{ ns}$)

Symbol	Parameter	Guaranteed Limit			Unit
		25 °C to -55°C	≤85°C	≤125°C	
t_{PLH}, t_{PHL}	Maximum Propagation Delay, Input D to Q (Figures 1 and 5)	30	38	45	ns
t_{PLH}, t_{PHL}	Maximum Propagation Delay, Latch Enable to Q (Figures 2 and 5)	30	38	45	ns
t_{PLZ}, t_{PHZ}	Maximum Propagation Delay, Output Enable to Q (Figures 3 and 6)	28	35	42	ns
t_{PZH}, t_{PZL}	Maximum Propagation Delay, Output Enable to Q (Figures 3 and 6)	28	35	42	ns
t_{TLH}, t_{THL}	Maximum Output Transition Time, Any Output (Figures 1 and 5)	12	15	18	ns
C_{IN}	Maximum Input Capacitance	10	10	10	pF
C_{OUT}	Maximum Three-State Output Capacitance (Output in High-Impedance State)	15	15	15	pF

C_{PD}	Power Dissipation Capacitance (Per Enabled Output)	Typical @25°C, $V_{CC} = 5.0 \text{ V}$	pF
	Used to determine the no-load dynamic power consumption: $P_D = C_{PD} V_{CC}^2 f + I_{CC} V_{CC}$	48	

TIMING REQUIREMENTS($V_{CC} = 5.0 \text{ V} \pm 10\%$, $C_L = 50 \text{ pF}$, Input $t_r = t_f = 6.0 \text{ ns}$)

Symbol	Parameter	Guaranteed Limit			Unit
		25 °C to -55°C	≤85°C	≤125°C	
t_{SU}	Minimum Setup Time, Input D to Latch Enable (Figure 4)	10	13	15	ns
t_h	Minimum Hold Time, Latch Enable to Input D (Figure 4)	5	5	5	ns
t_w	Minimum Pulse Width, Latch Enable (Figure 2)	15	19	22	ns
t_r, t_f	Maximum Input Rise and Fall Times (Figure 1)	500	500	500	ns

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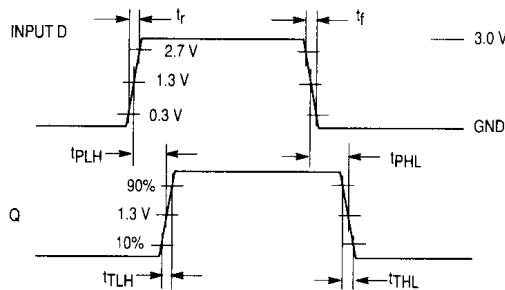


Figure 1. Switching Waveforms

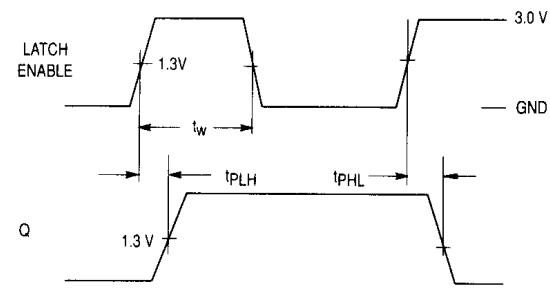


Figure 2. Switching Waveforms

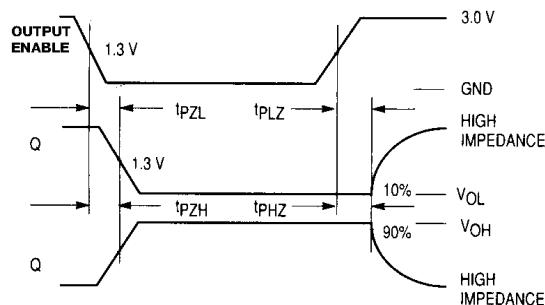


Figure 3. Switching Waveforms

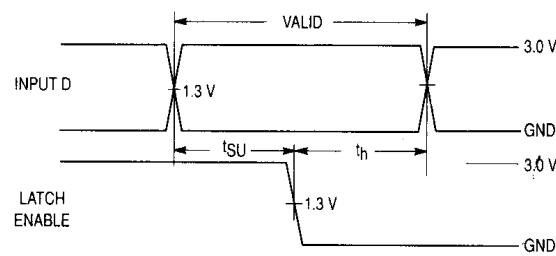
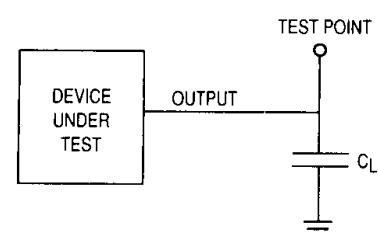
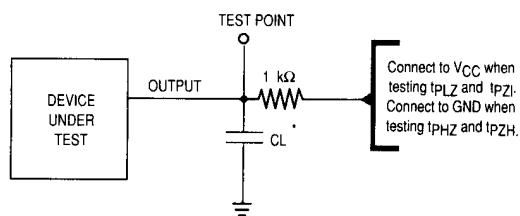


Figure 4. Switching Waveforms



* Includes all probe and jig capacitance

Figure 5. Test Circuit



* Includes all probe and jig capacitance

Figure 6. Test Circuit

